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Stocking Distributor

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[Chip Quik](#)
[SMDSWLF.031 4OZ](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

CHIPQUIK®

SMDSWLF.031 4OZ

Datasheet revision 1.0

www.chipquik.com

Solder Wire SAC305 No-Clean with 2.2% Flux Core 4oz Spool

Product Highlights

2.2% flux core
 Made from grade-A virgin metals
 Smaller Size
 RoHS II and REACH compliant

Specifications

Alloy: Sn96.5/Ag3.0/Cu0.5
 Wire Diameter: 0.031"
 Flux Type: No-Clean
 Flux Classification: ROL0
 Melting Point: 217-220°C (423-428°F)
 Packaging: 4 oz spool

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes): Yes
 J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): Yes
 RoHS 2 Directive 2011/65/EU: Yes